

3.5 x2.8mm SMD CHIP LED LAMP

P/N: KPED-3528SYC

SUPER BRIGHT YELLOW

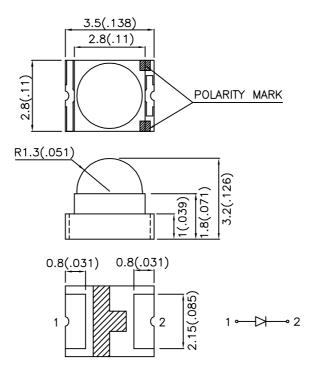
Features

- •SINGLE COLOR.
- •SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- •IDEAL FOR BACKLIGHTING.
- •AVAILABLE ON TAPE AND REEL.
- •PACKAGE: 500PCS / REEL.
- •RoHS COMPLIANT.

Description

The Super Bright Yellow device is made with DH InGaAIP (on GaAs substrate) light emitting diode chip.

Package Dimensions



- All dimensions are in millimeters (inches).
 Tolerance is ±0.2(0.008") unless otherwise noted.
- 3. Specifications are subject to change without notice.

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Selection Guide

Part No.	Dice	lv (mcd) @ 20mA		,	Viewing Angle
			Min. Typ.		201/2
KPED-3528SYC	SUPER BRIGHT YELLOW (InGaAIP)	WATER CLEAR	70	250	40°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD	Dominant Wavelength	Super Bright Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	28		nm	IF=20mA
С	Capacitance	Super Bright Yellow	25		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Yellow	2.0	2.5	V	IF=20mA
lR	Reverse Current	Super Bright Yellow		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Super Bright Yellow	Units	
Power dissipation	125	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

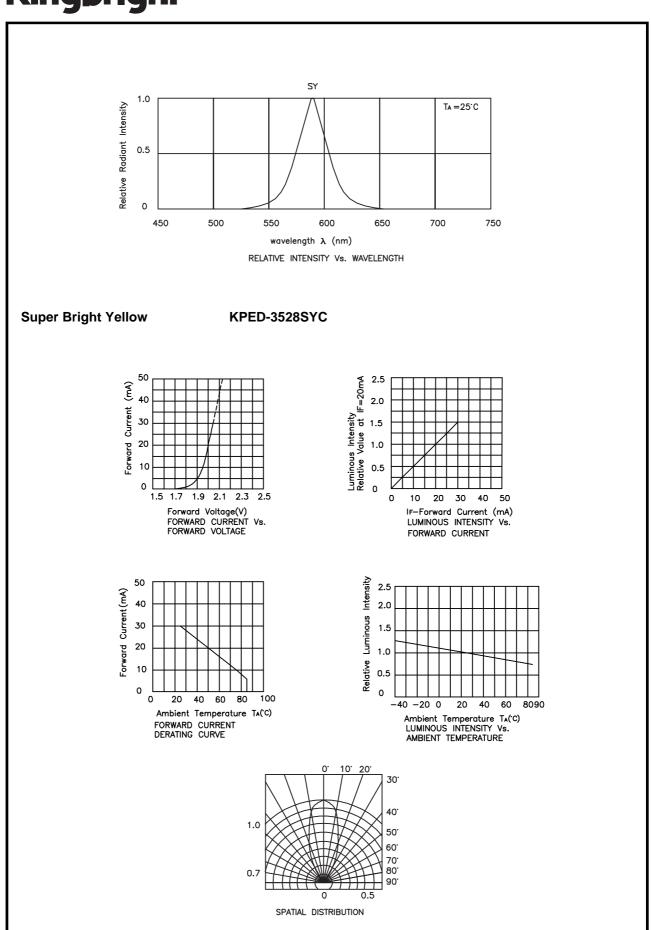
Note

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

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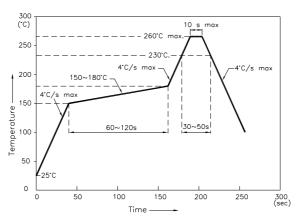


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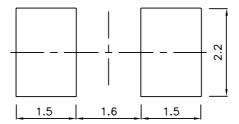
KPED-3528SYC

Reflow Soldering Profile For Lead-free SMT Process.

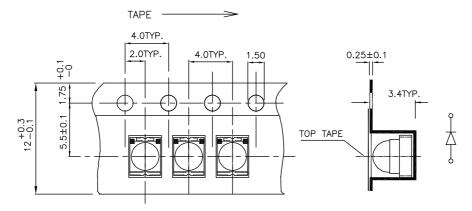


- NOTES: 1. We recommend the reflow temperature 245 $^{\circ}$ C(+/-5 $^{\circ}$ C). The maximum soldering temperature should be limited to 260°C.
 - 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity/ luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity/ Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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